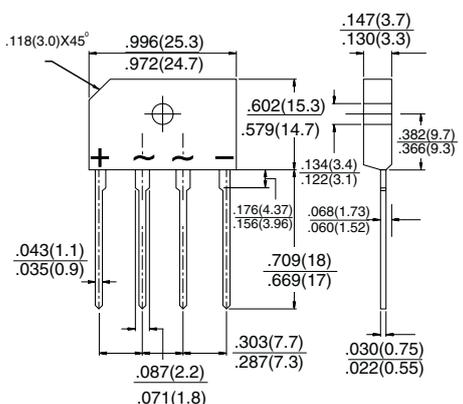


4.0 Amp. Glass Passivated Bridge

<p style="text-align: center;">Plastic Case</p>  <ul style="list-style-type: none"> • Mounting Instructions • High temperature soldering guaranteed: 260 °C – 10 sc. • Recommended mounting torque: 8 Kg.cm. 	<table style="width: 100%; border: none;"> <tr> <td style="text-align: center; width: 50%;">Voltage 400 to 1000 V.</td> <td style="text-align: center; width: 50%;">Current 4.0</td> </tr> </table> <div style="text-align: center; margin: 10px 0;">  </div> <ul style="list-style-type: none"> • Glass Passivated Junction Chips. • Lead and polarity identifications. • Case: Molded Plastic. • Ideal for printed circuit board (P.C.B.). • High surge current capability. • The plastic material carries U/L recognition 94 V-O. 	Voltage 400 to 1000 V.	Current 4.0
Voltage 400 to 1000 V.	Current 4.0		

Maximum Ratings, according to IEC publication No. 134

		D4SB 40	D4SB 60	D4SB 80	D4SB 100
V_{RRM}	Peak recurrent reverse voltage (V)	400	600	800	1000
V_{RMS}	Maximum RMS voltage (V)	280	420	560	700
$I_{F(AV)}$	Max. Average forward current with heatsink without heatsink	4.0 A at 115°C Tc. 3.0 A at 40 °C			
I_{FSM}	10 ms. peak forward surge current (Jedec Method)	150 A			
V_{DIS}	Dielectric strength (terminals to case, AC 1 min.)	2000 V			
I^2t	Current squared time (rating for fusing) (1ms.<t<10ms. Tc = 25°C)	110 A ² sec			
T_j	Operating temperature range	– 55 to + 150 °C			
T_{stg}	Storage temperature range	– 55 to +150 °C			

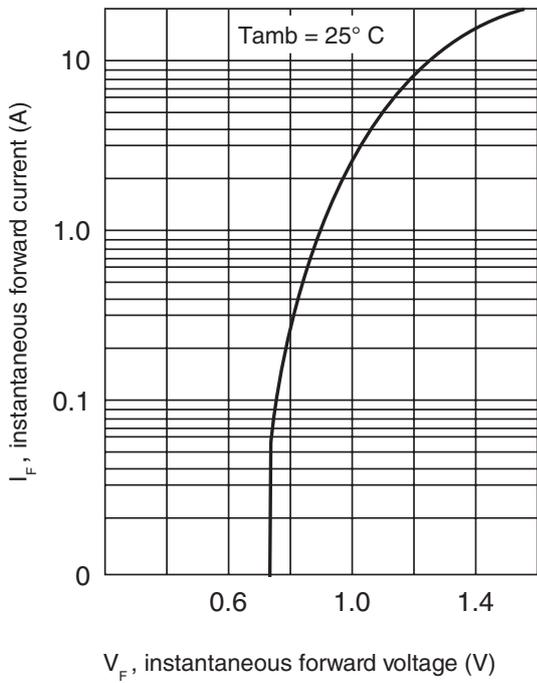
Electrical Characteristics at Tamb = 25°C

V_F	Max. forward voltage drop per diode at $I_F = 2.0 A$ $I_F = 4.0 A$	1.00V 1.10V
I_R	Max. instantaneous reverse current at V_{RRM}	5µA
MAXIMUM THERMAL RESISTANCE		
$R_{th(j-c)}$	Junction-Case. With Heatsink.	5.5 °C/W
$R_{th(j-a)}$	Junction-Ambient. Without Heatsink.	22 °C/W

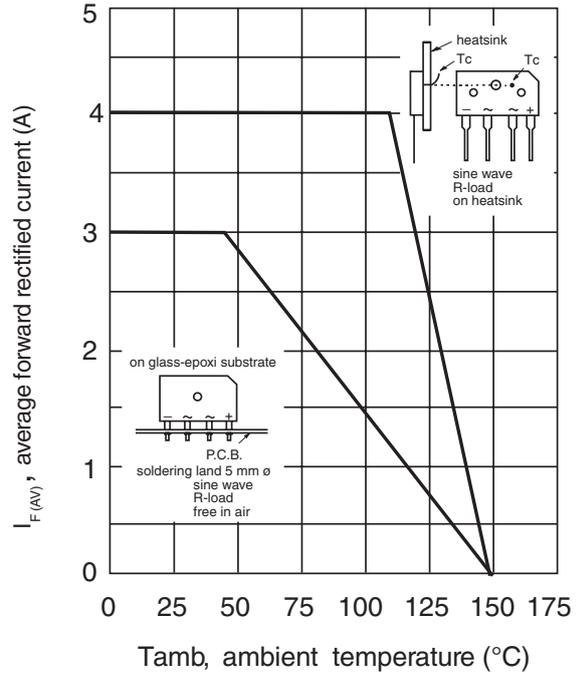
Rating And Characteristic Curves

Characteristic Curves

TYPICAL FORWARD CHARACTERISTIC



FORWARD CURRENT DERATING CURVE



MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

